Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK3544

### **Switching Regulator Applications**

• Low drain-source ON resistance: RDS (ON) =  $0.29 \Omega$  (typ.)

• High forward transfer admittance:  $|Y_{fs}| = 5.8 \text{ S (typ.)}$ 

• Low leakage current:  $I_{DSS} = 100 \,\mu\text{A} \,(\text{max}) \,(V_{DSS} = 450 \,\text{V})$ 

• Enhancement-mode:  $V_{th} = 3.0 \sim 5.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

### **Maximum Ratings (Ta = 25°C)**

Characteristics			Symbol	Rating	Unit	
Drain-source voltage			$V_{DSS}$	450	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )			$V_{DGR}$	450	V	
Gate-source voltage			V <sub>GSS</sub>	±30	٧	
Drain current	DC	(Note 1)	I <sub>D</sub>	13	Α	
	Pulse	(Note 1)	I <sub>DP</sub>	52	A	
Drain power dissipation (Tc = 25°C)			P <sub>D</sub>	100	W	
Single pulse avalanche energy (Note 2)			E <sub>AS</sub>	350	mJ	
Avalanche current			I <sub>AR</sub>	13	Α	
Repetitive avalanche energy (Note 3)			E <sub>AR</sub>	10	mJ	
Channel temperature			T <sub>ch</sub>	150	°C	
Storage temperature range			T <sub>stg</sub>	-55~150	°C	

# 1. GATE : G 2. N.C. 3. SOURCE: S 4. DRAIN : D JEDEC — JEITA SC-97 TOSHIBA 2-9F1B

Weight: 0.74 g (typ.)

### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.25	°C/W	

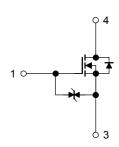
Note 1: Please use device on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD} = 90~V,~T_{ch} = 25^{\circ}C$  (initial), L = 3.46 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 13 A

Note 3: Repetitive rating; pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.

### **Circuit Configuration**





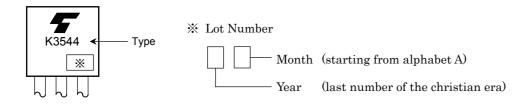
## **Electrical Characteristics (Tc = 25°C)**

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rent	I <sub>GSS</sub>	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Gate-source breakdown voltage		V (BR) GSS	$I_G = 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off curr	Drain cut-off current		V <sub>DS</sub> = 450 V, V <sub>GS</sub> = 0 V	_	_	100	μА
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	450	_	_	V
Gate threshold voltage		V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	3.0	_	5.0	V
Drain-source ON resistance		R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A	_	0.29	0.4	Ω
Forward transfer admittance		Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 6 A	3.0	5.8	_	S
Input capacitance		C <sub>iss</sub>		_	1600	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	17	_	
Output capacitance		Coss		_	220	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ $0 \text{ V}$ $V_{GS}$ $0 \text{ V}$ $0  V$	_	28		- ns
	Turn-on time	t <sub>on</sub>		_	45	_	
	Fall time	t <sub>f</sub>		_	10	_	
	Turn-off time	t <sub>off</sub>	Duty ≤ 1%, t <sub>W</sub> = 10 μs	_	56	_	
Total gate charge		Qg		_	34	_	nC
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \simeq 360 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}$	_	19	_	
Gate-drain charge		Q <sub>gd</sub>		_	15	_	

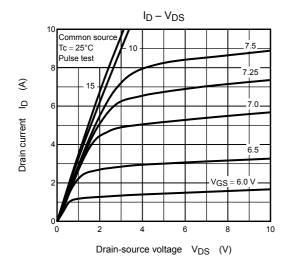
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

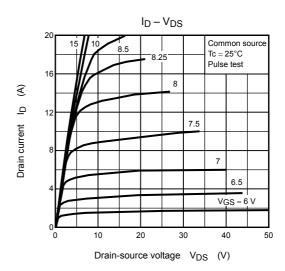
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	$I_{DR}$	_	_	_	13	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	52	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 13 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 13 A, V <sub>GS</sub> = 0 V,	_	300	_	ns
Reverse recovery charge	Qrr	dI <sub>DR</sub> /dt = 100 A/μs	_	3.4	_	μС

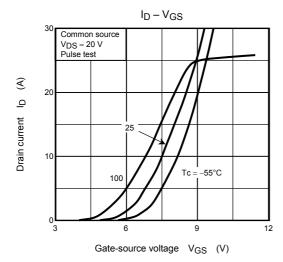
## Marking

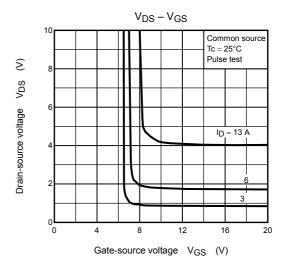


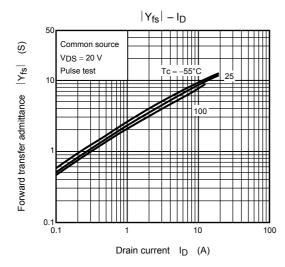
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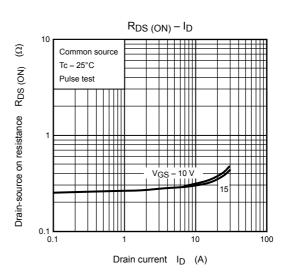


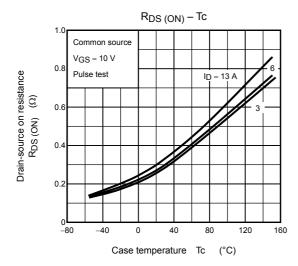


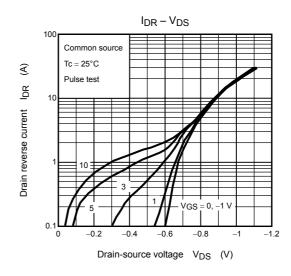


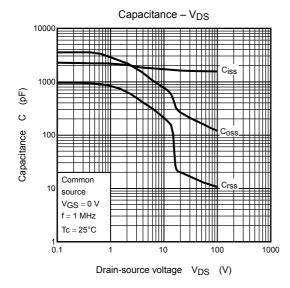


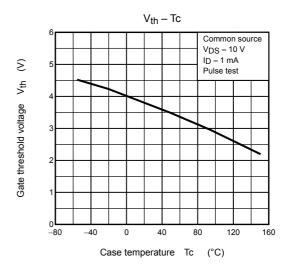


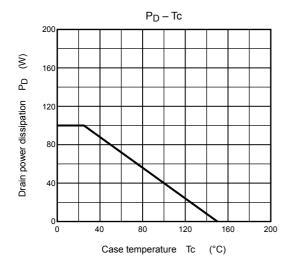


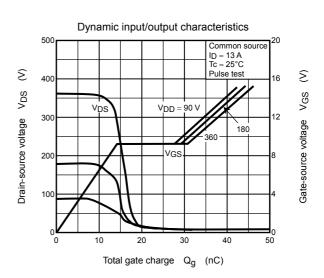


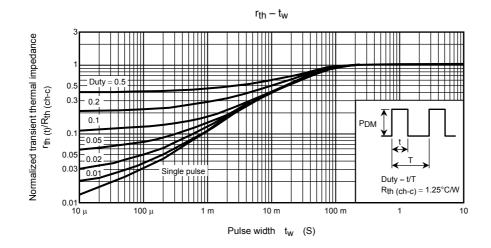


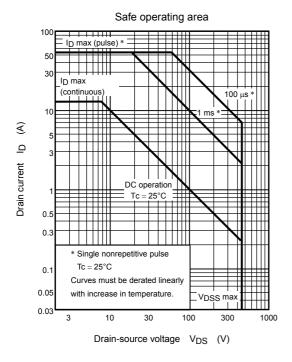


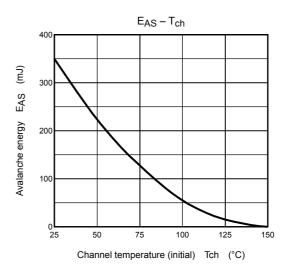


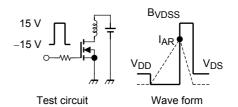












$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 3.46~mH \end{aligned} \qquad \text{EAS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{\text{BVDSS}}{\text{BVDSS} - \text{VDD}} \right)$$

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